

What is claimed is:

1. A needle fixture of a probe card in semiconductor inspection equipment comprising:
 - a printed circuit board;
 - a needle fixture installed in the printed circuit board;
 - a resin unit affixing a probe needle to the needle fixture using an adhesive; and
 - a separation preventer for preventing separation of the resin unit from the needle fixture, wherein the separation preventer includes:
 - a plurality of notches formed along a bottom surface of the needle fixture; and
 - the adhesive filling the plurality of notches.
2. The needle fixture of the probe card according to claim 1, wherein the adhesive is an epoxy resin.
3. The needle fixture of the probe card according to claim 1, wherein the plurality of notches are formed along the entire bottom surface of the needle fixture.
4. The needle fixture of the probe card according to claim 1, wherein a side sectional shape of the plurality of notches is a polygon.

5. The needle fixture of the probe card according to claim 4, wherein the polygon is a trapezoid.

6. The needle fixture of the probe card according to claim 1, wherein a side sectional shape of the plurality of notches is a curve.

7. The needle fixture of the probe card according to claim 6, wherein the curve has the shape of the Greek letter "Ω".

8. A needle fixing method in a probe card of semiconductor inspection equipment fixing a probe needle to a needle fixture using an adhesive, comprising:

forming a plurality of notches along a bottom surface of the needle fixture;

depositing a first resin layer on the bottom surface of the needle fixture to cover and fill the plurality of notches;

depositing a second resin layer on a predetermined position of the probe needle;

contacting an exposed bottom surface of the first resin layer with an exposed upper surface of the second resin layer; and

heating the first and the second resin layers to melt and fuse the first and second resin layers.

9. The needle fixing method in the probe card according to claim 8, wherein the adhesive is an epoxy resin.

10. The needle fixing method in the probe card according to claim 8, wherein depositing the first resin layer comprises:

depositing the first resin layer to a uniform predetermined thickness over and in the plurality of notches on the bottom surface of the needle fixture.

11. The needle fixing method in the probe card according to claim 8, wherein the plurality of notches are formed along the entire bottom surface of the needle fixture.

12. The needle fixing method in the probe card according to claim 8, wherein a side sectional shape of the plurality of notches is a polygon.

13. The needle fixing method in the probe card according to claim 12, wherein the polygon is a trapezoid.

14. The needle fixing method in the probe card according to claim 8, wherein a side sectional shape of the plurality of notches is a curve.

15. The needle fixing method in the probe card according to claim 14, wherein the curve has the shape of the Greek letter "Ω".